

# FMI12N60ES

**FUJI POWER MOSFET** 

# Super FAP-E<sup>3S</sup> series

# **N-CHANNEL SILICON POWER MOSFET**

#### ■ Features

Maintains both low power loss and low noise Lower R<sub>DS</sub>(on) characteristic More controllable switching dv/dt by gate resistance Smaller V<sub>GS</sub> ringing waveform during switching Narrow band of the gate threshold voltage (4.2±0.5V) High avalanche durability

## Applications

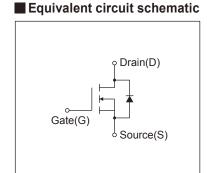
Switching regulators UPS (Uninterruptible Power Supply) DC-DC converters

## Maximum Ratings and Characteristics

# ● Absolute Maximum Ratings at Tc=25°C (unless otherwise specified)

# T-Pack(L) ① ② ③

■ Outline Drawings [mm]



Description	Symbol	Characteristics	Unit	Remarks	
Duain Course Voltage	V <sub>DS</sub>	600	V		
Drain-Source Voltage	V <sub>DSX</sub>	600	V	V <sub>GS</sub> = -30V	
Continuous Drain Current	I <sub>D</sub>	±12	A		
Pulsed Drain Current	IDP	±48	A		
Gate-Source Voltage	V <sub>GS</sub>	±30	V		
Repetitive and Non-Repetitive Maximum AvalancheCurrent	IAR	12	A	Note*1	
Non-Repetitive Maximum Avalanche Energy	Eas	384	mJ	Note*2	
Repetitive Maximum Avalanche Energy	Ear	18	mJ	Note*3	
Peak Diode Recovery dV/dt	dV/dt	4.4	kV/μs	Note*4	
Peak Diode Recovery -di/dt	-di/dt	100	A/µs	Note*5	
Maximum Power Dissipation	PD	1.67	W	Ta=25°C	
Maximum Power Dissipation		180	VV	Tc=25°C	
Oneveting and Stavens Temperature vanue	Tch	150	°C		
Operating and Storage Temperature range	Tstg	-55 to + 150	°C		
Isolation Voltage	Viso	2	kVrms	t = 60sec, f = 60Hz	

#### ● Electrical Characteristics at Tc=25°C (unless otherwise specified)

Description	Symbol	Conditions		min.	typ.	max.	Unit
Drain-Source Breakdown Voltage	BVDSS	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V		600	-	-	V
Gate Threshold Voltage	V <sub>GS</sub> (th)	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>	I <sub>D</sub> =250µA, V <sub>DS</sub> =V <sub>GS</sub>		4.2	4.7	V
Zero Gate Voltage Drain Current		V <sub>DS</sub> =600V, V <sub>GS</sub> =0V	Tch=25°C	-	-	25	μА
	IDSS	V <sub>DS</sub> =480V, V <sub>GS</sub> =0V	Tch=125°C	-	-	250	
Gate-Source Leakage Current	Igss	V <sub>GS</sub> =±30V, V <sub>DS</sub> =0V		-	10	100	nA
Drain-Source On-State Resistance	R <sub>DS</sub> (on)	I <sub>D</sub> =6A, V <sub>GS</sub> =10V		-	0.641	0.75	Ω
Forward Transconductance	<b>g</b> fs	I <sub>D</sub> =6A, V <sub>DS</sub> =25V	I <sub>D</sub> =6A, V <sub>DS</sub> =25V		8	-	S
Input Capacitance	Ciss	V <sub>DS</sub> =25V V <sub>GS</sub> =0V f=1MHz		-	1300	1950	pF
Output Capacitance	Coss			-	150	225	
Reverse Transfer Capacitance	Crss			-	8.5	13	
Turn-On Time	td(on)	V <sub>cc</sub> =300V V <sub>cs</sub> =10V I <sub>D</sub> =6A R <sub>6</sub> =27Ω		-	40	60	ns
	tr			-	40	60	
Turn-Off Time	td(off)			-	74	111	
	tf			-	19	29	
Total Gate Charge	Q <sub>G</sub>	14 00014	14 00014		37	56	nC
Gate-Source Charge	Qss	V <sub>cc</sub> =300V I <sub>D</sub> =12A - V <sub>GS</sub> =10V		-	15	23	
Gate-Drain Charge	Q <sub>GD</sub>			-	12	18	
Gate-Drain Crossover Charge	Qsw			-	6.5	10	
Avalanche Capability	lav	L=2.64mH, T <sub>ch</sub> =25°C		12	-	-	Α
Diode Forward On-Voltage	VsD	I <sub>F</sub> =12A, V <sub>GS</sub> =0V, T <sub>ch</sub> =25°C		-	0.86	1.30	V
Reverse Recovery Time	trr	I <sub>F</sub> =12A, V <sub>GS</sub> =0V		-	0.52	-	μS
Reverse Recovery Charge	Qrr	-di/dt=100A/μs, Tch=25°C		-	5.5	-	μC

#### Thermal Characteristics

Description	Symbol	Test Conditions	min.	typ.	max.	Unit
Thermal resistance	Rth (ch-c)	Channel to case			0.690	°C/W
	Rth (ch-a)	Channel to ambient			75.0	°C/W

Note \*1 : Tch≤150°C

Note \*2: Stating Tch=25°C, Ias=5A, L=28.2mH, Vcc=60V, R<sub>S</sub>=50Ω

Eas limited by maximum channel temperature and avalanche current.

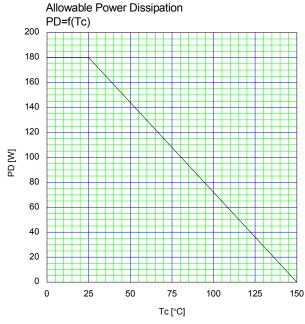
See to 'Avalanche Energy' graph.

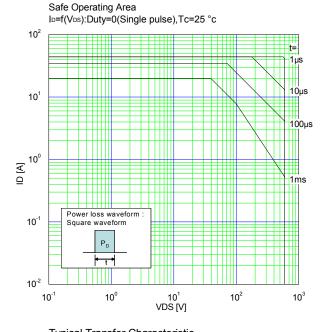
Note  $^{\star}3$  : Repetitive rating : Pulse width limited by maximum channel temperature

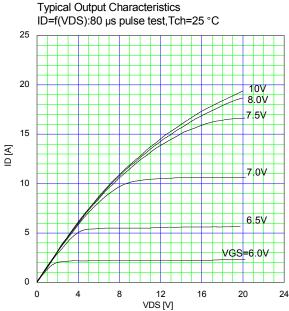
See to the 'Transient Themal impeadance' graph.

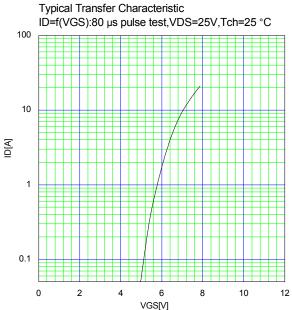
Note \*4 : Ir≤-Ip, -di/dt=100A/µs, Vcc≤BVbss, Tch≤150°C.

Note \*5 : Ir≤-Ip, dv/dt=4.4kV/µs, Vcc≤BVbss, Tch≤150°C.



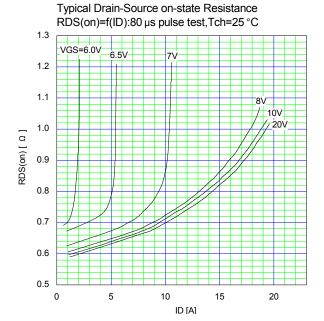


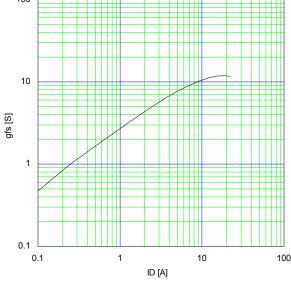




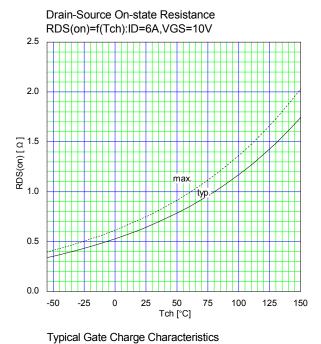


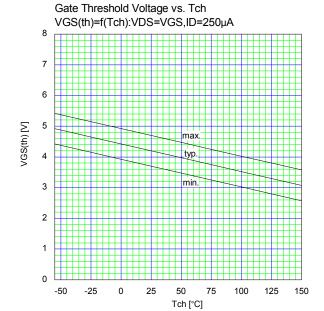
Typical Transconductance

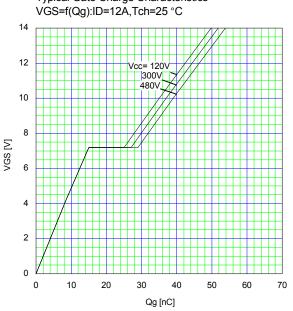


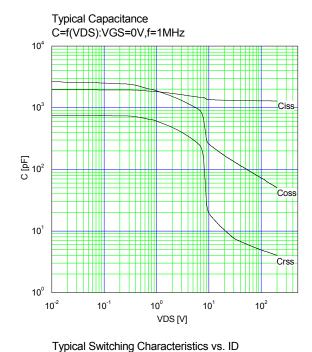


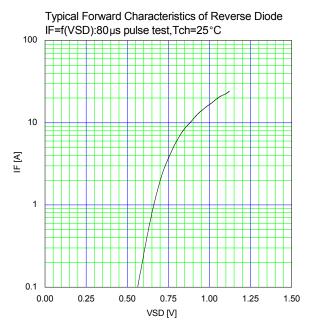
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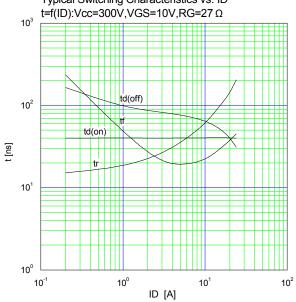


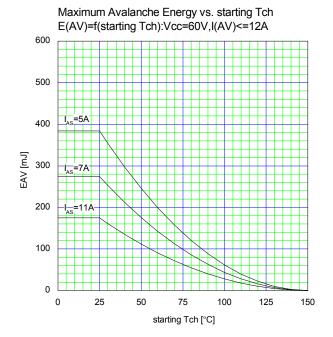


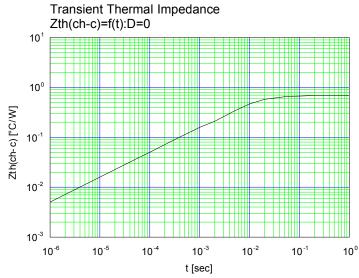












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- OA equipment

Audiovisual equipment

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